



 <p>Masach Technologies Board Level Shielding Design & fabrication</p>	Item No:	Description:	Material:
	MS183-10	DRAWN RF SHIELD FRAME + COVER	TIN STEEL (See Note 1-2)
	Note: (1) TS275E 8.4/8.4 (2) Electrolytic Tin Plate As Per EN 10202:2001 Min Tin Thickness 3.5 μ m (3) General tolerance ± 0.2 mm Non Dimensioned items remain Masach Technologies LTD property.		
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